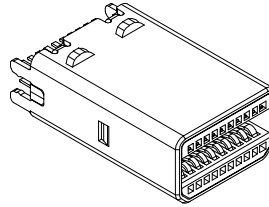
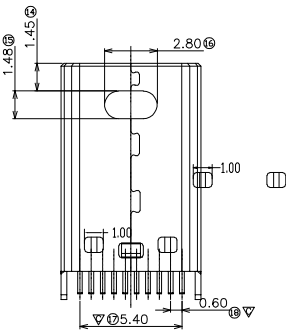
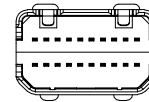
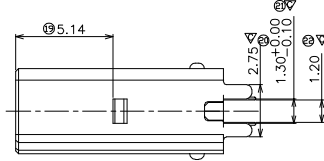
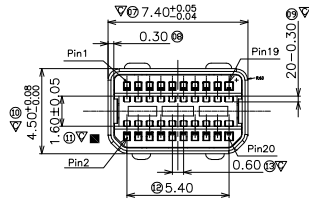
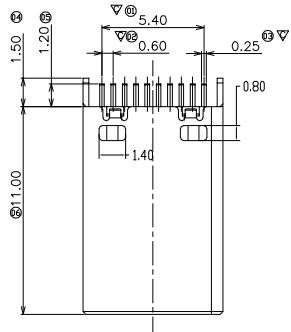
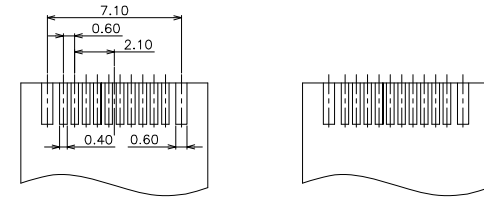


RoHS Compliant

REVISIONS			
REV.	DESCRIPTION	DATE	DESIGN



3D VIEW



标记▽为重点管控尺寸.

标记⊗为FAI尺寸.

标记■为CPK尺寸.

Top Row			Bottom Row		
Pin Number	Signal Type	Pin Name	Pin Number	Signal Type	Pin Name
1	GND	GND	2	In	HotPlug Detect
3	Out	ML_Lane 0(p)	4	CONFIG	CONFIG1
5	Out	ML_Lane 0(n)	6	CONFIG	CONFIG2
7	GND	GND	8	GND	GND
9	Out	ML_Lane 1(p)	10	Out	ML_Lane 3(p)
11	Out	ML_Lane 1(n)	12	Out	ML_Lane 3(n)
13	GND	GND	14	GND	GND
15	Out	ML_Lane 2(p)	16	I/O	AUX_CH(p)
17	Out	ML_Lane 2(n)	18	I/O	AUX_CH(n)
19	GND	GND	20	PWR Out	DP_PWR

备注: PCB LAYOUT

1. 材质

- 1.1 端子: C5191 镀GOLD FLESH半金雾锡;
- 1.2 胶芯: MODING LCP 黑色; 主体 LCP白色;
- 1.3 外壳: C2680 镀金 盐雾测试24H

2. 电气特性

- 2.1 额定电压:40VAC max.
- 2.2 额定电流 :0.5A.
- 2.3 接触阻抗 :30Milliohms Max.
- 2.4 绝缘阻抗 :100Megohms Min.
- 2.5 耐电压:300VAC.

3. 机械特性

- 3.1 插入力 :4.5Kgf max.
- 3.2 拔出力:1.0~4.0Kgf.
- 3.3 耐久:10,000 Cycles

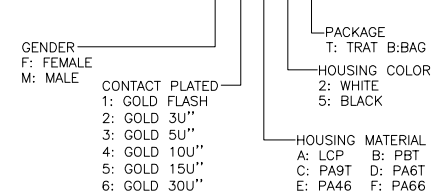
4. 环境特性

- 4.1 应用温度范围:-40°C to +85°C

5. 包装: 吸塑盘

PART NO. INFORMATION

MDP09- M X X X X - 003 - V2-B



Bestcreate Technology Limited

TOLERANCES UNLESS OTHERWISE SPECIFIED:

.X	± 0.25	X.*	± 3*
.XX	± 0.20	.X*	± 2*
.XXX	± 0.15	.XX*	± 1*

Website:www.bsc-elec.com

Email:bestcreate@bsc-elec.com

DESIGN: I.L DATE: 2017.3.1

CHECKED: C.W DATE: 2017.3.1

APPROVED: C.W DATE: 2017.3.1

TITLE: SPLINT 1.2MM MINI DP MALE CONNECTOR

MATERILA: PART NO: MDP09-MXXXX-003-V2-B SIZE: A4

FINSH: DWG NO: MDP09-MXXXX-003-V2-B

REV: A UNIT mm SCALE 1=1 QUALITY SYMBOLS